

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00460

REV: E1

SUN REV: Not In VersionControl

LAYER NAME= Top Layer

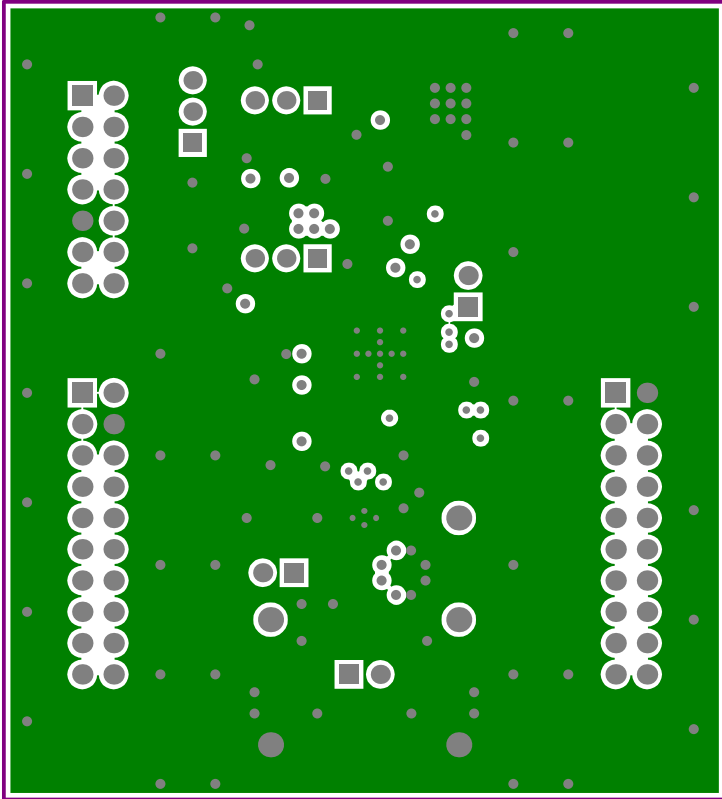
PLOT NAME=Top Layer

GENERATED

: 6/5/2015

4:06:20 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00460

REV: E1

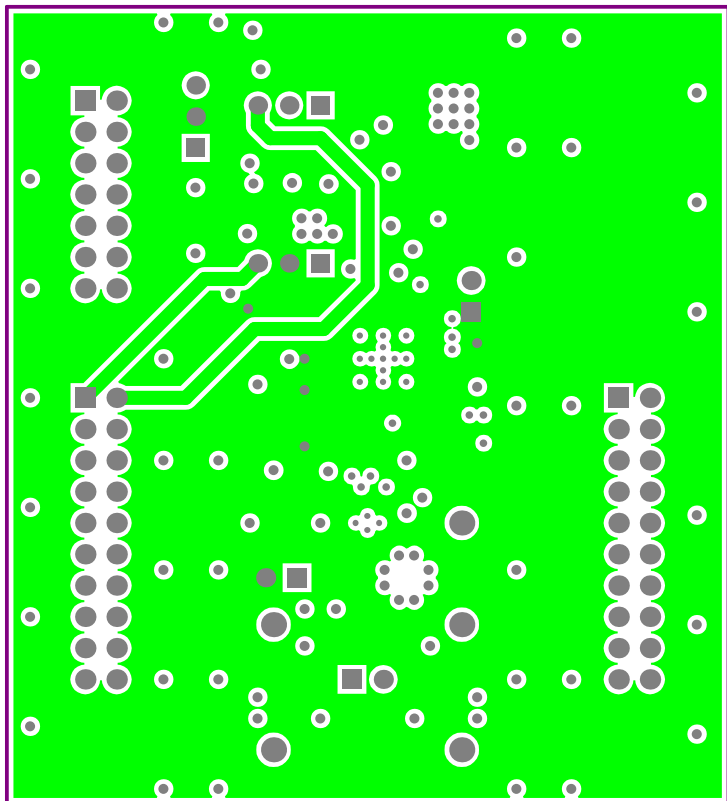
SUN REV: Not In VersionControl

LAYER NAME= MidLayer1 (GND)

PLOT NAME=MidLayer1 (GND)

GENERATED : 6/5/2015 4:06:21 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00460

REV: E1

SUN REV: Not In VersionControl

LAYER NAME= MidLayer2 (PWR)

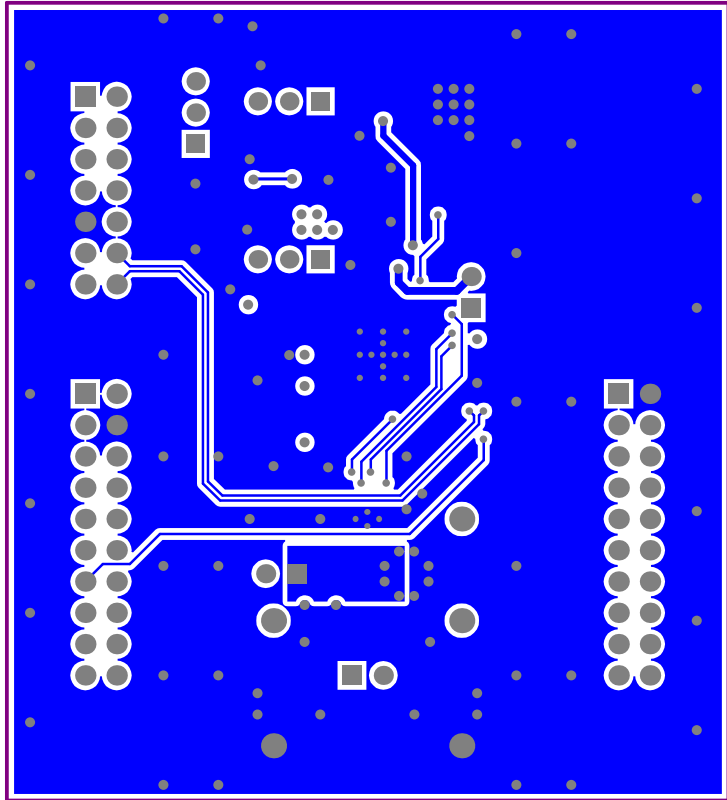
PLOT NAME=MidLayer2 (PWR)

GENERATED

: 6/5/2015

4:06:21 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00460

REV: E1

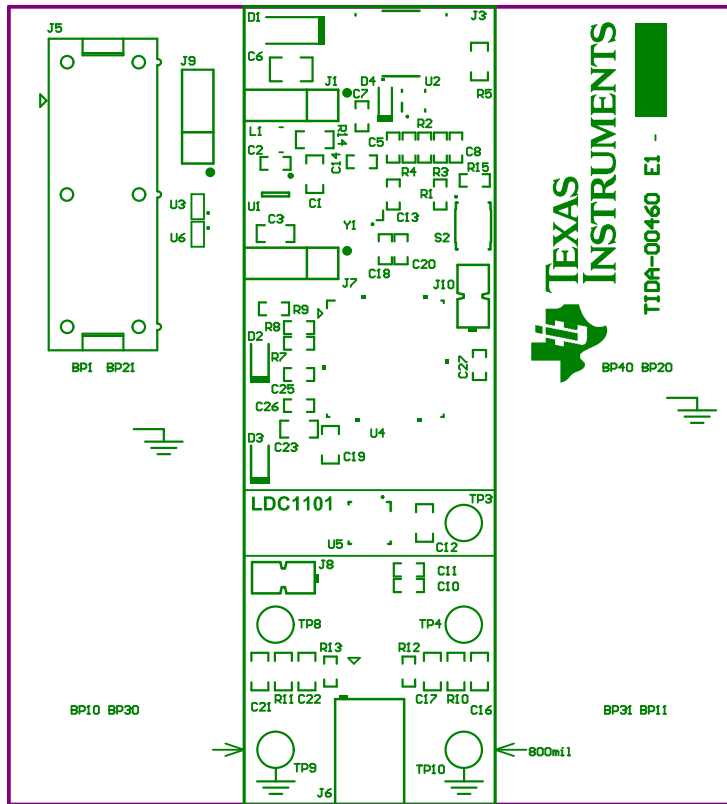
SUN REV: Not In VersionControl

LAYER NAME= Bottom Layer

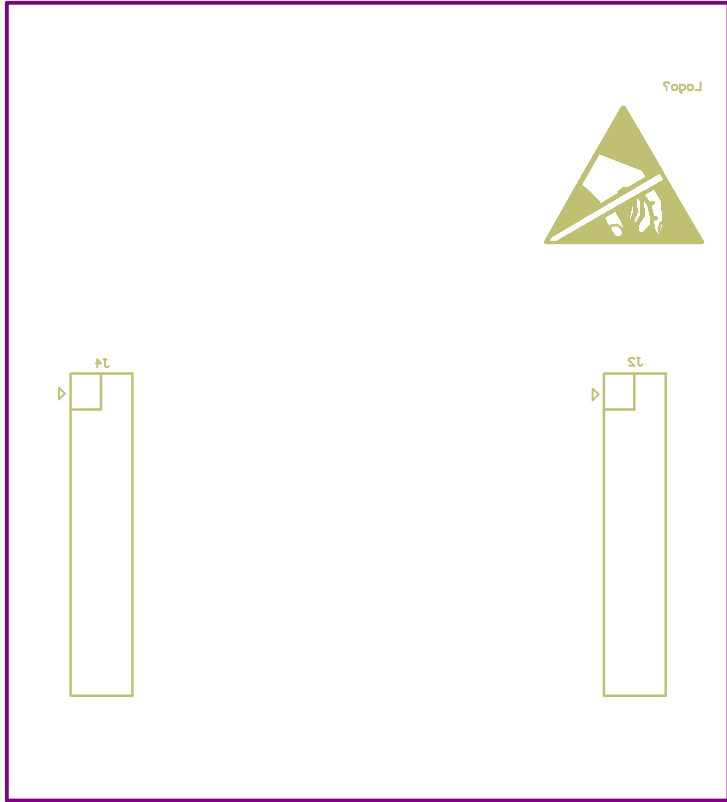
PLOT NAME=Bottom Layer

GENERATED : 6/5/2015 4:06:21 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00460	REV: E1	SUN REV: Not In VersionControl
LAYER NAME= Top Overlay			
PLOT NAME=Top Silkscreen Overlay	GENERATED : 6/5/2015	4:06:21 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00460

REV: E1

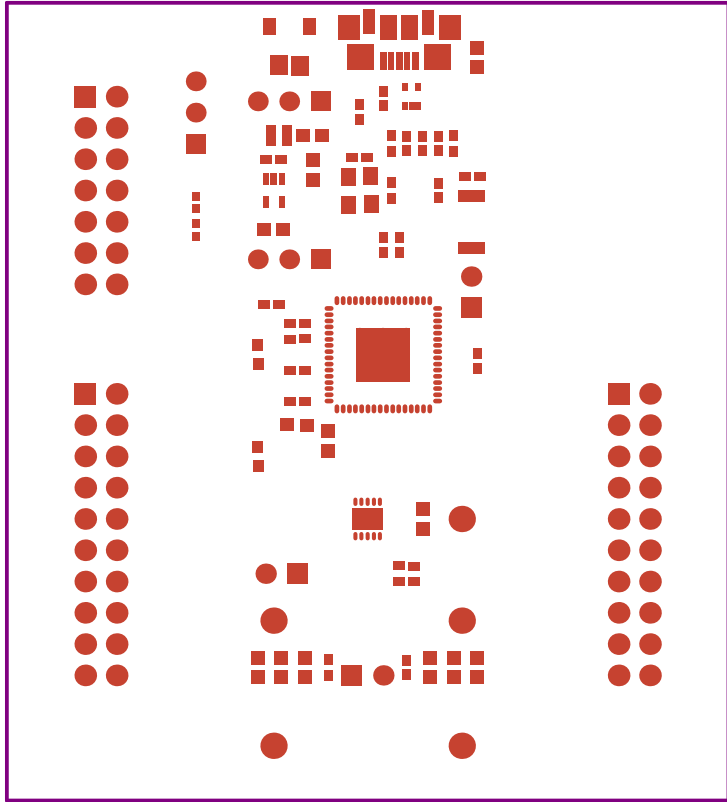
SUN REV: Not In VersionControl

LAYER NAME= Bottom Overlay

PLOT NAME=Bottom Silkscreen Overlay

GENERATED : 6/5/2015 4:06:21 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00460

REV: E1

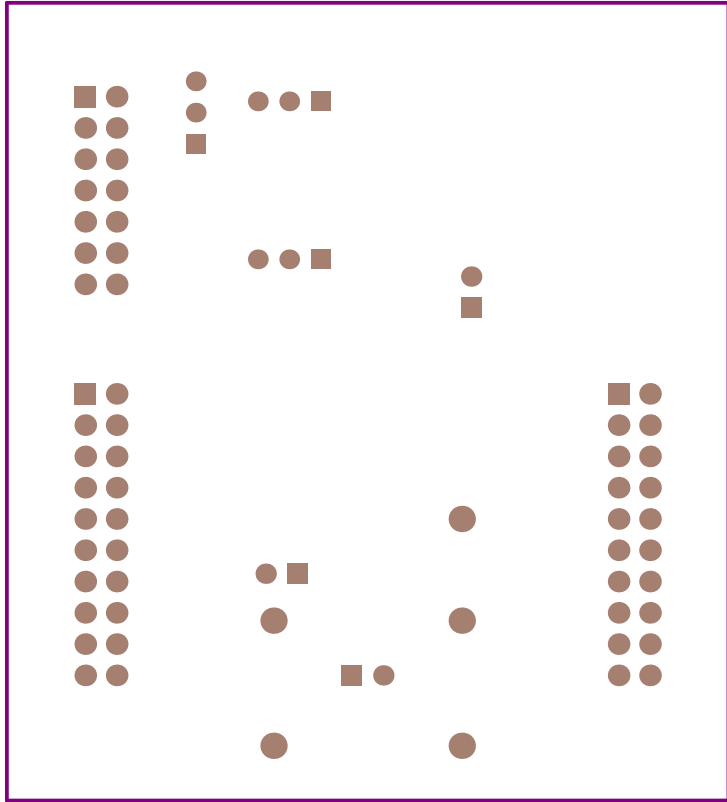
SUN REV: Not In VersionControl

LAYER NAME= Top Solder

PLOT NAME=Top Solder Mask Print

GENERATED : 6/5/2015 4:06:22 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00460

REV: E1

SUN REV: Not In VersionControl

LAYER NAME= Bottom Solder

PLOT NAME=Bottom Solder Mask Print

GENERATED : 6/5/2015 4:06:22 PM

TEXAS INSTRUMENTS

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